

ABSTRACT

A thermal interface material may be covalently bonded to a bottom surface of a heat dissipating device and/or a backside surface of a heat generating device. The heat dissipating device may be thermally coupled to the heat generating device, the thermal interface material disposed between the bottom surface of the heat dissipating device and the backside surface of the heat generating device. The thermal interface material may comprise a polymer material with thermally conductive filler components dispersed therein. For one embodiment, the thermally conductive filler components may be covalently bonded together. For one embodiment, the thermally conductive filler components may be covalently bonded with the polymer material.